

Claim 14. (twice amended) Thermoplastic adhesive film comprising

- D1
- (i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,
 - ii)
 - a) one or more tackifying resins in a proportion of from 5 to 50% by weight or
 - b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or
 - c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,
- and
- iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,
 - iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film, and
- wherein the adhesive film is in the form of a punched film section.

D2

Claim 15 (twice amended). A method for implanting electrical modules in

a card body provided with a cutout for accommodating an electronic module which on a first side has a plurality of contact surfaces and on a second side, which is opposite the first side, has an IC chip whose terminals are connected via electrical conductors to the contact surfaces, wherein an electrically conductive,

thermoplastic and heat-activatable adhesive film, comprising

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 - c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,
 - and
 - iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,
 - iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film

is used to connect the second side of the module to the card body.

REMARKS

This amendment is being filed to place claims 14 and 15 in independent form. No new matter or new issues are involved, as the only changes made to place claims 14 and 15 into independent form was to add the limitations of claim 9, from which they originally depended, to them. The word "the" (two occurrences) has also been corrected to --a-- in claim 15.